

Appl. No. 10/563,778  
 Request for Corrected Assignment dated 10/19/2006  
 Attorney Docket No. 1217-053827

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No. : 10/563,778 Confirmation No. 3140  
 Applicants : Naoya SAIKI  
 Filed : January 6, 2006  
 Title : Hardenable Pressure Sensitive Adhesive Sheet for Dicing/Die-Bonding and Method for Manufacturing Semiconductor Device  
 Art Unit : 1734  
 Customer No. : 28289

FACSIMILE NO. 703-305-9822  
 Office of Initial Patent Examination's  
 Filing Receipt Corrections  
 Commissioner for Patents  
 P.O. Box 1450  
 Alexandria, VA 22313-1450

REQUEST FOR CORRECTED FILING RECEIPT

Sir:

Attached is a marked-up copy of the official Filing Receipt for the above-identified patent application for which a Corrected Filing Receipt is hereby requested.

The Foreign Applications data is missing. It should include the following Japanese Application Information

--Japan 2003-271950 07/08/2003--

A copy of the Declaration and Power of Attorney for Patent Application filed with the application on January 6, 2006 listing the complete Foreign Priority Information is also attached. No fee is due, as there was no error on the Applicant's part.

Respectfully submitted,  
 THE WEBB LAW FIRM

By



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CERTIFICATE OF FACSIMILE TRANSMISSION

I hereby certify that this correspondence is being facsimile transmitted to U.S. Patent and Trademark Office, P.O. Box 1450, Alexandria, VA 22313-1450 on October 19, 2006.

\_\_\_\_\_  
 Michael L. Vertullo  
 (Name of Person Mailing Paper)

  
 Michael L. Vertullo  
 Signature  
 Date  
 10/19/2006



**UNITED STATES PATENT AND TRADEMARK OFFICE**

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APPL NO.	FILING QR 371 (c) DATE	ART UNIT	FIL FEE REC'D	ATTY.DOCKET NO	DRAWINGS	TOT CLMS	IND CLMS
10/563,778	01/06/2006	1734	900	1217-Q53827		17	1

**CONFIRMATION NO. 3140**

28289  
THE WEBB LAW FIRM, P.C.  
700 KOPPERS BUILDING  
436 SEVENTH AVENUE  
PITTSBURGH, PA 15219

**FILING RECEIPT**



OC000000019854081\*

Date Mailed: 08/02/2006

Receipt is acknowledged of this regular Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please mail to the Commissioner for Patents P.O. Box 1450 Alexandria Va 22313-1450. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

**Applicant(s)**

Naoya Saiki, Saitama, JAPAN;

**Assignment For Published Patent Application**

Lintec Corporation, Tokyo, JAPAN

**Power of Attorney:** The patent practitioners associated with Customer Number 28289.

**Domestic Priority data as claimed by applicant**

This application is a 371 of PCT/JP04/09629 07/07/2004

**Foreign Applications** JAPAN 2003-271950 08/07/2003

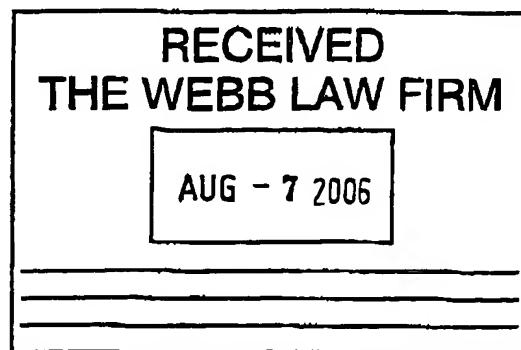
If Required, Foreign Filing License Granted: 08/01/2006

The country code and number of your priority application, to be used for filing abroad under the Paris Convention, is **US10/563,778**

**Projected Publication Date:** 11/09/2006.

**Non-Publication Request:** No

**Early Publication Request:** No



**Title**

Hardenable pressure sensitive adhesive sheet for dicing/die-bonding and method for manufacturing semiconductor device

**Preliminary Class**

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**PROTECTING YOUR INVENTION OUTSIDE THE UNITED STATES**

Since the rights granted by a U.S. patent extend only throughout the territory of the United States and have no effect in a foreign country, an inventor who wishes patent protection in another country must apply for a patent in a specific country or in regional patent offices. Applicants may wish to consider the filing of an international application under the Patent Cooperation Treaty (PCT). An international (PCT) application generally has the same effect as a regular national patent application in each PCT-member country. The PCT process simplifies the filing of patent applications on the same invention in member countries, but does not result in a grant of "an international patent" and does not eliminate the need of applicants to file additional documents and fees in countries where patent protection is desired.

Almost every country has its own patent law, and a person desiring a patent in a particular country must make an application for patent in that country in accordance with its particular laws. Since the laws of many countries differ in various respects from the patent law of the United States, applicants are advised to seek guidance from specific foreign countries to ensure that patent rights are not lost prematurely.

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Applicants may wish to consult the USPTO booklet, "General Information Concerning Patents" (specifically, the section entitled "Treaties and Foreign Patents") for more information on timeframes and deadlines for filing foreign patent applications. The guide is available either by contacting the USPTO Contact Center at 800-786-9199, or it can be viewed on the USPTO website at <http://www.uspto.gov/web/offices/pac/doc/general/index.html>.

For information on preventing theft of your intellectual property (patents, trademarks and copyrights), you may wish to consult the U.S. Government website, <http://www.stopfakes.gov>. Part of a Department of Commerce initiative, this website includes self-help "toolkits" giving innovators guidance on how to protect intellectual property in specific countries such as China, Korea and Mexico. For questions regarding patent enforcement issues, applicants may call the U.S. Government hotline at 1-866-999-HALT (1-866-999-4158).

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Title 35, United States Code, Section 184  
Title 37, Code of Federal Regulations, 5.11 & 5.15**

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## Declaration and Power of Attorney for Patent Application

### English Language Declaration

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled **DICING AND DIE BONDING PRESSURE-SENSITIVE ADHESIVE SHEET AND PROCESS FOR PRODUCING SEMICONDUCTOR DEVICES**

The specification of which

is attached hereto.  
 was filed on \_\_\_\_\_  
as Application Serial No. \_\_\_\_\_  
and was amended on \_\_\_\_\_ (if applicable)  
 was filed as PCT international application  
No. PCT/JP2004/9629 on July 7, 2004  
and was amended under PCT Article 19 on \_\_\_\_\_ (if applicable)

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the patentability of this application in accordance with Title 37, Code of Federal Regulations, §1.56(a).

I hereby claim foreign priority benefits under Title 35, United States Code, §119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s)

**Priority Claimed**

I hereby claim the benefit under Title 35, United States Code, §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, §1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application: